



Material Composition Declaration

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This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.

Adobe Reader version 7.0.5 is required to complete this declaration.

1752-2 1.1	IPC Web Site for Information on IPC-1752 Standard http://www.ipc.org/IPC-175x	Form Type * Distribute	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Informat
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Supplier Information

Company Name * RAMI Technology USA, LLC	Company Unique ID	Unique ID Authority	Response Date * 2016-07-12	Response Document ID				
Contact Name * YG Jiao	Title - Contact Quality Manager	Phone - Contact * +1 (305) 593-6033	Email - Contact * ygjiao@ramitechnology.com	<input type="button" value="Duplicate Contact -> Authorized Representative"/>				
Authorized Representative * John D. Ivens	Title - Representative QA Director	Phone - Representative * +1 (305) 593-6033	Email - Representative * john.iven@ramitechnology.com	Supplier Comments or URL for Additional Information				
Requester Item Number	Mfr Item Number	Mfr Item Name	Effective Date	Version	Manufacturing Site	Weight *	UOM	Unit Type
VCSO family	VCSO family	Voltage Control SAW Oscillator	2021-02-04		Miami, Florida	194.807	mg	Each
Alternate Recommendation				Alternate Item Comments				

Manufacturing Process Information

Terminal Plating / Grid Array Material Gold (Au)	Terminal Base Alloy CU Alloy	J-STD-020 MSL Rating 1	Peak Process Body Temperature 265 C	Max Time at Peak Temperature 10 seconds	Number of Reflow Cycles 3
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Comments

Save the fields in this form to a file

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Clear all of the fields on this form

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Lock Supplier Fields

RoHS Material Composition Declaration

Declaration Type *

Simplified

RoHS Directive 2002/95/EC

RoHS Definition: Quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material for Cadmium

Supplier certifies that it gathered the information it provides in this form concerning RoHS restrictive substances using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

RoHS Declaration *

1 - Item(s) does not contain RoHS restricted substances per the definition above

Supplier Acceptance *

Accepted

Exemptions: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.

Declaration Signature

Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.

Supplier Digital Signature

YG Jiao

数字签名人 YG Jiao
DN: cn=YG Jiao, o=CN-中国, ou=RAMI TECHNOLOGY USA LLC, ou=QA Manager, email=ygjiao@ramistechnology.com
日期: 2016.07.14 13:38:54 +0800

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Line Functions: +I Inserts a New Item /SubItem +M Inserts a new Material +C Inserts a new Substance Category +S Inserts a new Substance - Deletes the element line

		Item/SubItem Name		Homogeneous Material		Weight	Unit of Measure	Level		Substance Category			Substance	CAS	Exempt	Weight	Unit of Measure	Tolerance		PPM		
																		-	+			
+I	-I	PCB		+M	-M	PC Board	82.695	mg	+C	-C	Supplier	PCB Material	+S	-S	Epoxy Resin	24969-06-0		39.276	mg			
													+S	-S	Glass Wool	65997-17-3		33.274	mg			
													+S	-S	Copper	7440-50-8		8.139	mg			
													+S	-S	Nickel	7440-02.0		0.652	mg			
													+S	-S	Gold	7440-57-5		0.108	mg			
													+S	-S	Misc	No CAS		1.246	mg			
+I	-I	Cover		+M	-M	Cover Nickel S	45.52	mg	+C	-C	Supplier	Cover Material	+S	-S	Copper	7440-50-8		25.036	mg			
													+S	-S	Zinc	7440-66-6		12.29	mg			
													+S	-S	Nickel	7440.02.0		8.194	mg			
+I	-I	Resistor, 0201		+M	-M	Chip Resistor	0.884	mg	+C	-C	Supplier	Material	+S	-S	Al2O3	1344-28-1		0.834	mg			
													+S	-S	RuO2	12036-10-1		0.012	mg			
													+S	-S	GlassFrit	65997-18-4		0.003	mg			
													+S	-S	Silver	7440-22-4		0.007	mg			
													+S	-S	Tin	7440-31-5		0.008	mg			
													+S	-S	Nickel	7440.02.0		0.014	mg			
													+S	-S	Epoxy	25068-38-6		0.003	mg			
													+S	-S	Misc	No CAS		0.003	mg			
+I	-I	Capacitor, 0201		+M	-M	Ceramic Capacit	1.003	mg	+C	-C	Supplier	Material	+S	-S	TiO2	13463-67-7		0.888	mg			
													+S	-S	Nickel	7440.02.0		0.006	mg			
													+S	-S	Tin	7440-31.5		0.013	mg			
													+S	-S	Silver	7440-22-4		0.096	mg			
+I	-I	IC		+M	-M	IC Package	8.98	mg	+C	-C	Supplier	material	+S	-S	Quartz (SiO)	14808-60-7		6.093	mg			
													+S	-S	Silicon	7440-21-3		0.182	mg			

+S	-S	Epoxy Condensate	1229915-25		0.713	mg															
+S	-S	Carbon	7440-44-0		0.021	mg															
+S	-S	Resin	No CAS		0.421	mg															
+C	-C	Supplier	IC Terminals	+S	-S	Copper	7440-50-8	0.826	mg												
				+S	-S	Gold	7440-57-5	0.335	mg												
				+S	-S	Silver	7440-22-4	0.146	mg												
				+S	-S	Tin	744031-5	0.243	mg												
+I	-I	SAW, 3x3mm	+M	-M	SAW	51.725	mg	+C	-C	Supplier	Wafer	+S	-S	SiO2	7631-86-9	7.4	mg				
								+C	-C	Supplier	Cover	+S	-S	Iron	7439-89-6	3.9594	mg				
												+S	-S	Ni	7440.02.0	2.2498	mg				
												+S	-S	Cobalt	7440.48-4	2.2498	mg				
												+S	-S	Manganese	7439.96-5	0.381	mg				
								+C	-C	Supplier	Base	+S	-S	Al2O3	1344-28-1	22.3145	mg				
												+S	-S	Iron	7439-89-6	2.996	mg				
												+S	-S	Tungsten	7440.33-7	2.5247	mg				
												+S	-S	Ni	7440.02.0	2.1	mg				
												+S	-S	Cobalt	7448-48-4	1.1202	mg				
												+S	-S	Cr2O3	1308-38-9	0.8694	mg				
												+S	-S	Silver	7440-22-4	0.5183	mg				
												+S	-S	Gold	7440-57-5	0.2709	mg				
												+S	-S	Molybdenum	7439-98-7	0.1404	mg				
												+S	-S	Copper	7440-50-8	0.5819	mg				
								+C	-C	Supplier	Wire	+S	-S	Aluminum	7429-90-5	0.54	mg				
												+S	-S	Silicon	7440-21-3	0.005	mg				
								+C	-C	Supplier	adhesive	+S	-S	Phenolic resin	9003-35-4	1.5	mg				
+I	-I	Solder	+M	-M	Solder SAC305	4	mg	+C	-C	Supplier	Metals	+S	-S	Tin	7440-31-5	3.86	mg				
												+S	-S	Silver	7440-22-4	0.12	mg				
												+S	-S	Copper	7440-50-8	0.02	mg				